

HM67-B5R0LF summary material content, BI Technologies Corporation

Index	Item	Material Name	Element Composition	CAS No	Material Mass (mg)	Composition (mg)
1	CORE	Toroid Core	Nickel Zinc Ferrite	12645-50-0	50	49
			Manganese-Zinc	13645-49-7		1
2	ADHESIVE	Epoxy	Bisphenol Type Epoxy Resin	-	15	7.2
			Brominated Type Epoxy Resin	-		3.75
			Hardener	Confidential		1.5
			Inorganic Filter	471-34-ect		1.5
			Antimony Oxide	1369-64-4		0.75
			Colouring Agent	1333-86-4,8016-11-3		0.3
3	WIRE	NY UEW-H	Copper	7440-50-8	20	19.4
			Polyurethane (PU)	-		0.4
			Polyamide (PA)	-		0.2
4	BODY	Header	Polyphenylene Sulfide	26125-40-6	180	46.8
			Inorganic Fillers And Additives	-		131.4
			Organic Fillers And Additives	-		1.8
			Carbon Black	1333-86-4		0.9
5	SOLDER	Lead Free Solder	Tin (Sn)	7440-31-5	8	7.64
			Silver (Ag)	7440-21-3		0.304
			Copper (Cu)	7440-50-8		0.056
Total Weight					273	

HM67-S250LF summary material content, BI Technologies Corporation

Index	Item	Material Name	Element Composition	CAS No	Material Mass (mg)	Composition (mg)
1	CORE	Toroid Core	Nickel Zinc Ferrite	12645-50-0	50	49
			Manganese-Zinc	13645-49-7		1
2	ADHESIVE	Epoxy	Bisphenol Type Epoxy Resin	-	15	7.2
			Brominated Type Epoxy Resin	-		3.75
			Hardener	Confidential		1.5
			Inorganic Filter	471-34-ect		1.5
			Antimony Oxide	1369-64-4		0.75
			Colouring Agent	1333-86-4,8016-11-3		0.3
3	WIRE	NY UEW-H	Copper	7440-50-8	55	53.35
			Polyurethane (PU)	-		1.1
			Polyamide (PA)	-		0.55
4	BODY	Header	Polyphenylene Sulfide	26125-40-6	180	46.8
			Inorganic Fillers And Additives	-		131.4
			Organic Fillers And Additives	-		1.8
			Carbon Black	1333-86-4		0.9
5	SOLDER	Lead Free Solder	Tin (Sn)	7440-31-5	8	7.64
			Silver (Ag)	7440-21-3		0.304
			Copper (Cu)	7440-50-8		0.056

Total Weight	308
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